Qualcom

RF360 Europe GmbH

Data sheet

Micro-acoustic extractor GNSS

Series/type:	B8666
Ordering code:	B39162B8666L210
Date:	January 30, 2019
Version:	2.16

DCN: 80-PA243-252 Rev. B

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1 Application

- Premium-performance BeiDou/GPS/Glonass Extractor with single ended 50 Ω ports
- Ultra-low-loss acoustic structure
- Advanced fully-integrated multiplexer structure (no external matching needed)
- Using common antenna for BeiDou/GPS/Glonass and Cellular bands
- Placed between antenna and cellular front-end switches and filters
- Usable GNSS pass bands: 1559.05
 -1563.144 MHz, 1574.42-1576.42 MHz, 1597.55-1605.89 MHz
- Usable CELL pass bands: 566 1510.9 MHz, 1710 – 2690 MHz, 3400 – 3800 MHz
- No switches and control lines required

2 Features

- Package size 1.7 mm × 1.3 mm
- Package height 0.5 mm
- Approximate weight 2 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

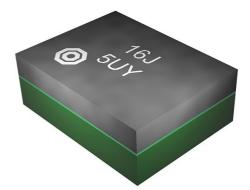
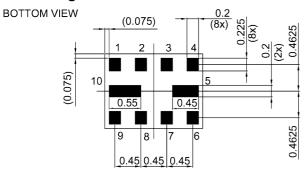


Figure 1: Picture of component with example of product marking.

3 Package



Pad and pitch tolerance ±0.05

Pin configuration 4

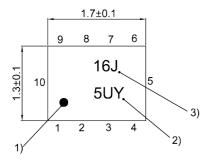
- 1 ANT
- BeiDou/GPS/Glonass(GNSS) 4
- CELL 9
- **■** 2, 3, 5, 6, Ground

7, 8, 10

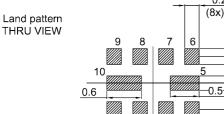
SIDE VIEW

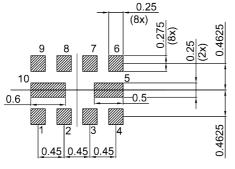


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number





Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.6 mm (max.). See Sec. Package information (p. 24).



5 Matching circuit

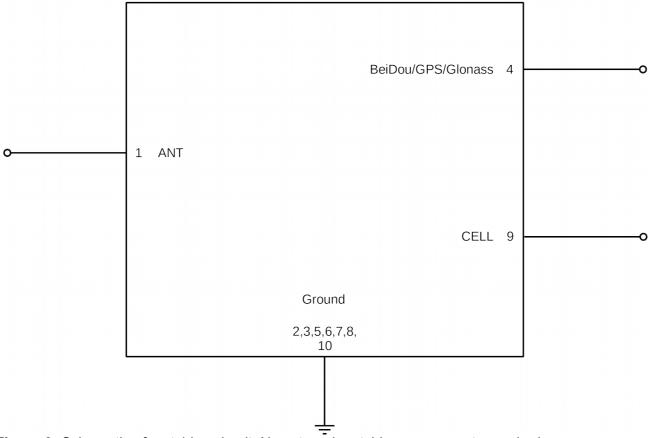


Figure 3: Schematic of matching circuit. No external matching components required.

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6 Characteristics ANT – GNSS

Temperature range for specification	$T_{_{\rm SPEC}}$	= −30 °C +85 °C
ANT terminating impedance	Z	= 50 Ω
GNSS terminating impedance	Z _{GNSS}	= 50 Ω
CELL terminating impedance		= 50 Ω

Characteristics ANT – GNSS				min. for $T_{\rm SPEC}$	typ. @ +25 °C	max. for $T_{_{ m SPEC}}$	
Insertion loss			α				
	1559.052 1563.144	4 MHz			1.2	2.6	dB
	1574.42 1576.42	MHz			0.8	1.5	dB
	1597.55 1605.89	MHz		—	1.5	3.5	dB
Attenuation			α				
	100 777	MHz		33	38	_	dB
	777 787	MHz		33	47	_	dB
	787 960	MHz		33	44	_	dB
	1427.9 1462.9	MHz		32	41	_	dB
	1710 1910	MHz		34	40	_	dB
	1910 2025	MHz		33	39	_	dB
	2110 2170	MHz		30	38	_	dB
	2300 2500	MHz		30	38	_	dB
	2500 2690	MHz		29	36	—	dB
	3400 3800	MHz			27	_	dB
VSWR			VSWR				
@ ANT port	1559.052 1563.144	4 MHz		—	1.2	2.0	
	1574.42 1576.42	MHz			1.3	2.0	
	1597.55 1605.89	MHz		—	1.4	2.0	
@ GNSS port	1559.052 1563.144	4 MHz		—	1.3	2.1	
	1574.42 1576.42	MHz		—	1.3	2.0	
	1597.55 1605.89	MHz		—	1.3	2.0	

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7 Characteristics ANT – CELL

Temperature range for specification	$T_{_{ m SPEC}}$	= −30 °C +85 °C
ANT terminating impedance	Z _{ANT}	= 50 Ω
GNSS terminating impedance	Z _{GNSS}	= 50 Ω
CELL terminating impedance	Z _{CELL}	= 50 Ω

Characteristics ANT – CELL			min. for $T_{\rm SPEC}$	typ. @ +25 °C	max. for $T_{_{\rm SPEC}}$	
Insertion loss		C				
	566 626	MHz	—	2.1	3.2	dB
	699 824	MHz	—	0.95	1.9	dB
	824 960	MHz	—	0.65	1.5	dB
	1427.9 1510.9	MHz	—	0.7	1.7	dB
	1710 1850	MHz	_	1.2	1.8	dB
	1850 2025	MHz	—	1.1	1.7	dB
	2110 2170	MHz	—	1.2	1.9	dB
	2300 2400	MHz	_	1.0	1.6	dB
	2400 2690	MHz	_	0.8	1.5	dB
	3400 3600	MHz	—	1.1	—	dB
	3600 3800	MHz	_	1.3	_	dB
Attenuation		C	r I			
	1559.052 1563.144	MHz	5	10		dB
	1574.42 1576.42	MHz	11	19	_	dB
	1597.55 1605.89	MHz	5	13	_	dB
VSWR		VSWR	2			
@ ANT port	566 626	MHz	_	1.6	2.3	
	699 824	MHz	_	1.1	2.0	
	824 960	MHz	_	1.1	2.0	
	1427.9 1510.9	MHz	_	1.6	2.1	
	1710 2025	MHz	_	1.3	2.0	
	2110 2170	MHz	_	1.3	2.0	
	2300 2400	MHz	_	1.3	2.0	
	2400 2690	MHz	_	1.2	2.0	
	3400 3600	MHz	_	1.7	_	
	3600 3800	MHz	_	1.8	_	
@ CELL port	566 626	MHz	_	1.4	2.2	
	699 824	MHz	_	1.2	2.0	
	824 960	MHz	—	1.1	2.0	
	1427.9 1510.9	MHz	—	1.6	2.1	
	1710 2025	MHz	—	1.5	2.1	
	2110 2170	MHz	—	1.4	2.0	
	2300 2400	MHz	—	1.4	2.0	
	2400 2690	MHz		1.3	2.0	

Please read **Cautions and warnings** and **Important notes** at the end of this document.



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Characteristics ANT – CELL	min. for $T_{_{ m SPEC}}$	typ. @ +25 °C	max. for $T_{\rm SPEC}$	
3400 3600 MHz		1.7	—	
3600 3800 MHz	—	1.9	—	

8 Characteristics GNSS – CELL

Temperature range for specification	T _{SPEC}	= −30 °C +85 °C
ANT terminating impedance	Z _{ANT}	= 50 Ω
GNSS terminating impedance	Z _{GNSS}	= 50 Ω
CELL terminating impedance	Z	= 50 Ω

Characteristics GNSS – CELL			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Isolation		α				
	566 777	MHz	34	48		dB
	777 787	MHz	34	48	_	dB
	787 960	MHz	34	45	_	dB
	1427.9 1462.9	MHz	31	40	_	dB
	1710 1990	MHz	36	44	_	dB
	2110 2170	MHz	37	45	_	dB
	2400 2690	MHz	32	40	_	dB
	3400 3800	MHz	—	31	—	dB

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9 **Maximum ratings**

Storage temperature	$T_{\rm STG}^{1)} = -40 ^{\circ}{\rm C} \dots +85 ^{\circ}{\rm C}$	
DC voltage	$ V_{\rm DC} = 5.0 \rm V (max.)^{2}$	
ESD voltage		
	V _{ESD} ³⁾ = 50 V (max.)	Machine model.
	V _{ESD} ⁴⁾ = 350 V (max.)	Human body model.
	V _{ESD} ⁵⁾ = 600 V (max.)	Charged device model.
Input power	P _{IN}	
@ CELL port: 566 626 MHz	28 dBm	Continuous wave for 5000 h @ 55 °C.
@ CELL port: 699 915 MHz	27 dBm	Continuous wave for 5000 h @ 55 °C.
@ CELL port: 824 849 MHz	35 dBm	GSM signal duty cycle 1:8 for 5000 h @ 55 °C. Effective power in On-state.
@ CELL port: 880 915 MHz	35 dBm	GSM signal duty cycle 1:8 for 5000 h @ 55 °C. Effective power in On-state.
@ CELL port: 1710 1785 MHz	33 dBm	GSM signal duty cycle 1:8 for 5000 h @ 55 °C.
@ CELL port: 1710 2690 MHz	27 dBm	Continuous wave for 5000 h @ 55 °C.
@ CELL port: 1850 1910 MHz	33 dBm	GSM signal duty cycle 1:8 for 5000 h @ 55 °C. Effective power in On-state.

1) Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

2) 168h Damp Heat Steady State acc. to IEC60068-2-67 Cy.

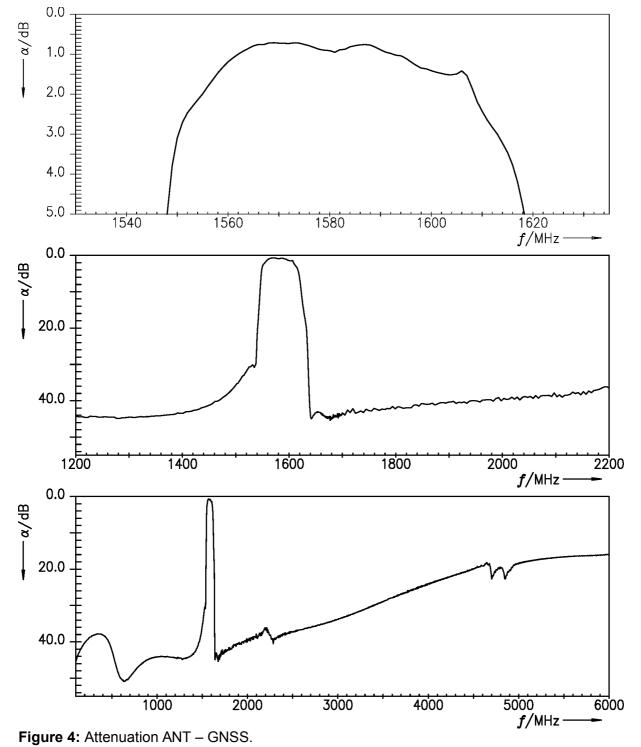
3) According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

4)

According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse. According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses. 5)

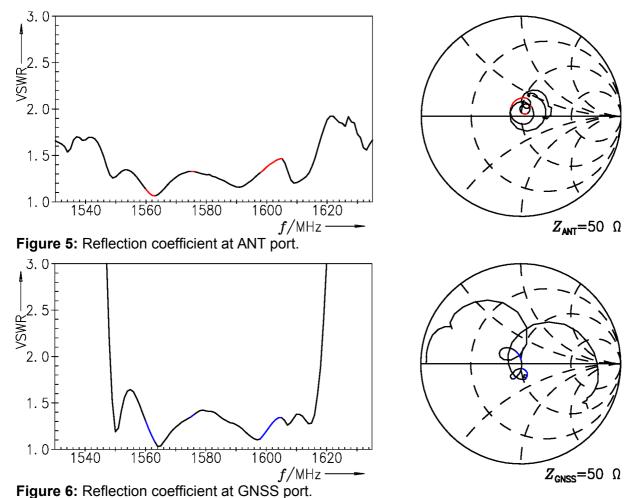


10 Transmission coefficient ANT – GNSS



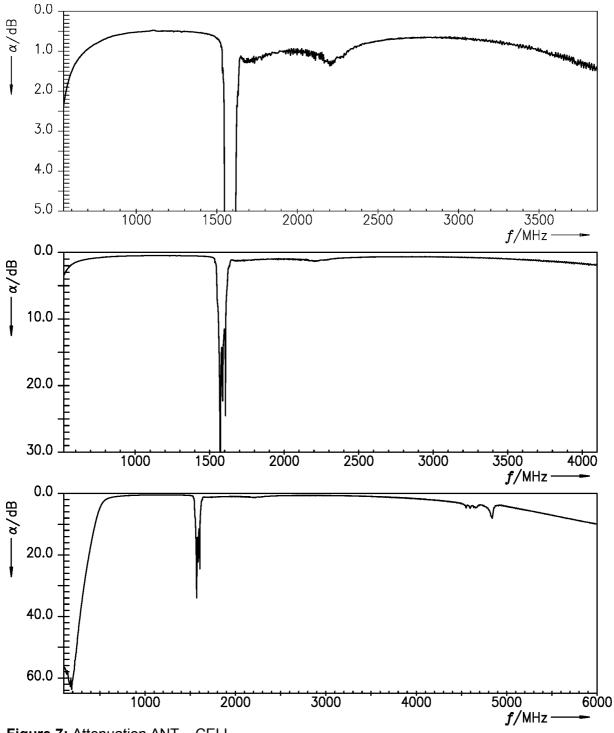


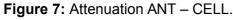
11 Reflection coefficients ANT – GNSS





12 Transmission coefficient ANT – CELL

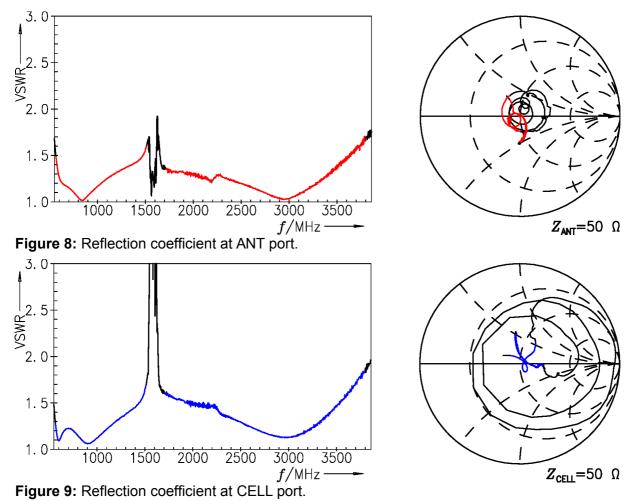




Please read Cautions and warnings and Important notes at the end of this document.

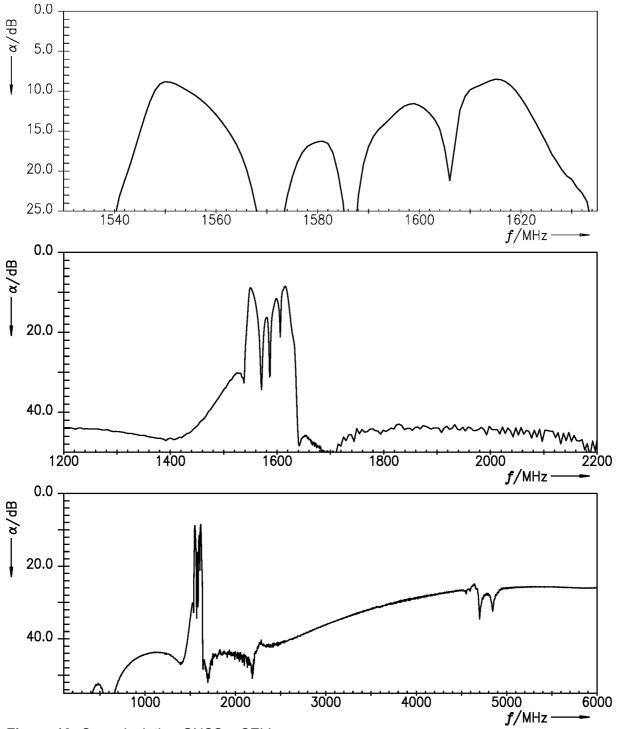


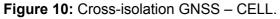
13 Reflection coefficients ANT - CELL





14 Transmission coefficient GNSS – CELL

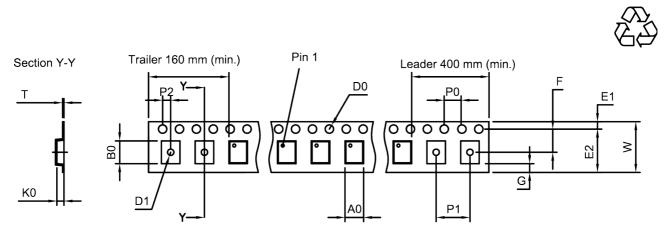






15 Packing material

15.1 Tape



User direction of unreeling

Figure 11: Drawing of tape (first-angle projection) is for illustration only and not to scale. Tape Dimensions in Table 1 are the valid dimensions for the tape.

 $\begin{array}{c|c} A_0 & 1.52 \pm 0.05 \text{ mm} \\ \hline B_0 & 1.94 \pm 0.05 \text{ mm} \\ \hline D_0 & 1.55 \pm 0.05 \text{ mm} \\ \hline D_1 & 0.50 \pm 0.05 \text{ mm} \\ \hline E_1 & 1.75 \pm 0.1 \text{ mm} \end{array}$

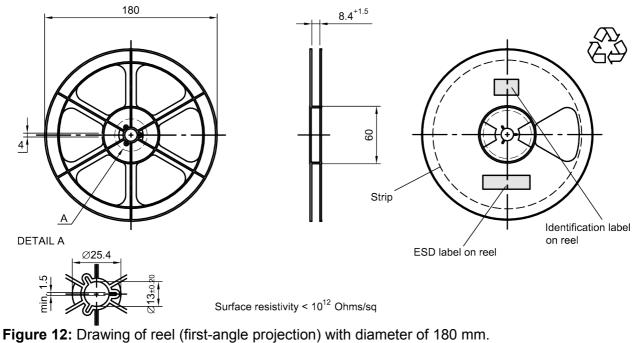
E2	6.25 mm (min.)
F	3.5±0.05 mm
G	0.75 mm (min.)
K_0	0.62±0.05 mm
P ₀	4.0±0.1 mm

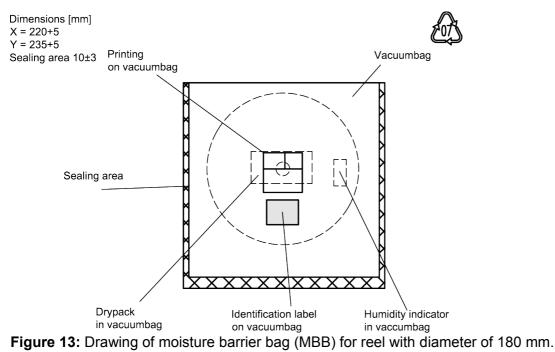
P ₁	4.0±0.1 mm
P_2	2.0±0.1 mm
Т	0.25±0.03 mm
W	8.0+0.3/-0 mm

Table 1: Tape dimensions.



15.2 Reel with diameter of 180 mm





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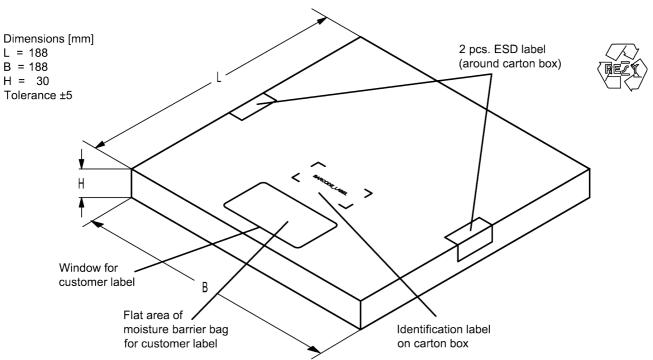


Figure 14: Drawing of folding box for reel with diameter of 180 mm.

15.3 Reel with diameter of 330 mm

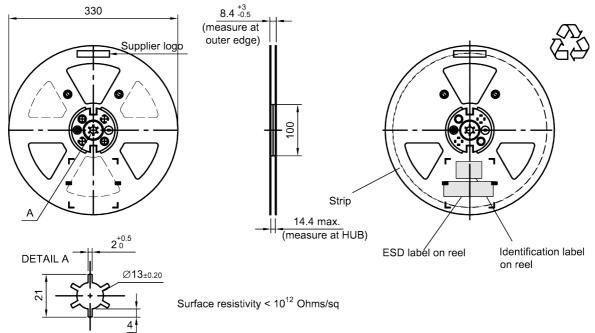


Figure 15: Drawing of reel (first-angle projection) with diameter of 330 mm.



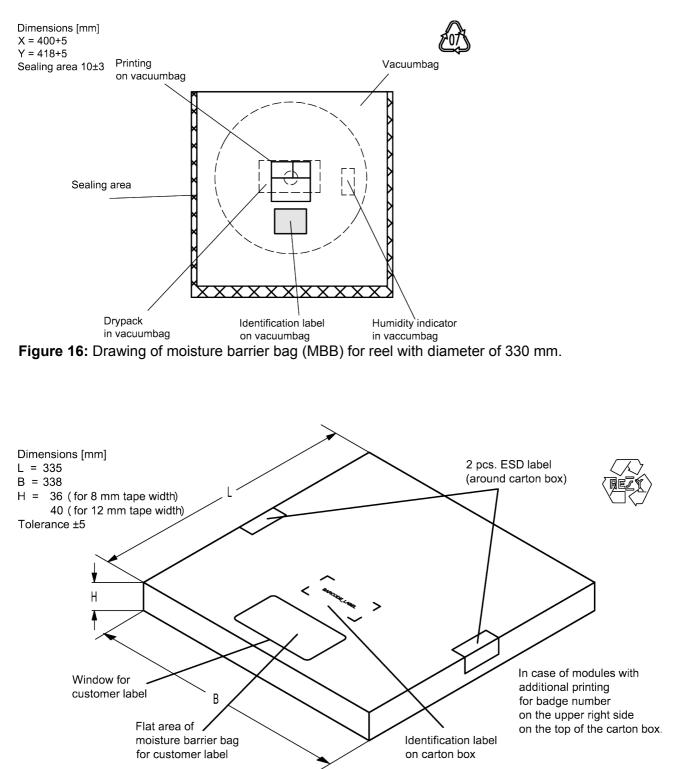


Figure 17: Drawing of folding box for reel with diameter of 330 mm.

16 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number is encoded by a special	e.g., B3xxxxB <u>1234</u> xxxx,	
Example of decoding 16J	type number marking on device =>	in decimal code. 1234
1 x 32 ² + 6 x The BASE32 code for pr	1234	

■ Lot number:

The last 5 digits of the lot number, 12345, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device **5UY**

decoding lot number marking on device		in decimal code.
5UY	=>	12345
5 x 47 ² + 27 (=U) x 47 ¹ + 31 (=Y) x 47 ⁰	=	12345

Adopted BASE32 code for type number			
Decimal	Base32	Decimal	Base32
value	code	value	code
0	0	16	G
1	1	17	Н
2	2	18	J
3	3	19	K
4	4	20	М
5	5	21	N
6	6	22	Р
7	7	23	Q
8	8	24	R
9	9	25	S
10	А	26	Т
11	В	27	V
12	С	28	W
13	D	29	Х
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal	Base47	Decimal	Base47
value	code	value	code
0	0	24	R
1	1	25	S
2	2	26	Т
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	Х
7	7	31	Y
8	8	32	Z
9	9	33	b
10	Α	34	d
11	В	35	f
12	С	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	Н	41	١
18	J	42	?
19	К	43	{
20	L	44	}
21	М	45	<
22	N	46	>
23	Р		

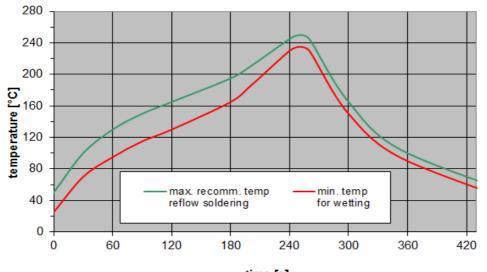
Table 2: Lists for encoding and decoding of marking.

17 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
<i>T</i> > 220 °C	30 s to 70 s
<i>T</i> > 230 °C	min. 10 s
<i>T</i> > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T _{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



time [s] Figure 18: Recommended reflow profile for convection and infrared soldering – lead-free solder.

18 Annotations

18.1 Matching coils

See TDK inductor pdf-catalog <u>http://www.tdk.co.jp/tefe02/coil.htm#aname1</u> and Data Library for circuit simulation <u>http://www.tdk.co.jp/etvcl/index.htm</u>.

18.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

18.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

18.4 Ordering codes and packing units

Ordering code	Packing unit
B39162B8666L210	15000 pcs
B39162B8666L210S 5	5000 pcs

 Table 4: Ordering codes and packing units.

19 Cautions and warnings

19.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <u>www.rf360jv.com/orderingcodes</u>.

19.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

19.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

19.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

20 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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